


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	AMS/21/12662	
1.3 Title of PCI	Power Management BU: L4960 and L200CV assembled in ST Bouskoura (Morocco) with a new Molding Compound	
1.4 Product Category	See product list	
1.5 Issue date	2021-03-08	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marcello SAN BIAGIO
2.1.2 Marketing Manager	Salvatore DI VINCENZO
2.1.3 Quality Manager	Giuseppe LISI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Mold compound	ST Bouskoura (Morocco)

4. Description of change

	Old	New
4.1 Description	Molding compound : SAMSUNG SI-7200DXC	Molding compound : SUMITOMO EME-6650RL1L
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No changes of the Electrical Characteristics and Quality.	

5. Reason / motivation for change

5.1 Motivation	Following the announcement of products obsolescence in the PTN#12276 having as last buy order April 1st, 2021, we are obliged to communicate the replacement of the current mold compound SAMSUNG SI-7200DXC with a new one SUMITOMO EME-6650RL1L because of its unavailability to cover all the requests. Then you could receive parts that have been produced by using both mold compound. It goes without saying that parts with the new mold compound have the same Electrical Characteristics and Quality Level.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	The traceability of the new parts will be ensured by different internal codification and QA number
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7. Timing / schedule

7.1 Date of qualification results	2021-03-04
7.2 Intended start of delivery	2021-04-10
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	12662 W1153-20-New Resin Sumitomo for L200_L740 M05-KSAD-L7651 Pentawatt_Heptawatt assembled in Bouskoura.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2021-03-08
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9. Attachments (additional documentations)

12662 Public product.pdf
 12662 W1153-20-New Resin Sumitomo for L200_L740 M05-KSAD-L7651 Pentawatt_ Heptawatt assembled in Bouskoura.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L200CV	
	L4960	

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